

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Franz LAERMER et al.
Serial No. : 10/530,612
Filed : December 30, 2005
For : **PLASMA SYSTEM AND METHOD FOR
ANISOTROPICALLY ETCHING STRUCTURES
INTO A SUBSTRATE**

Art Unit : 1792
Examiner : Maki A. Angadi
Confirmation No. : 6739

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I hereby certify that this correspondence is being electronically transmitted to the United States Patent and Trademark Office via the Office electronic filing system on May 4, 2009.
Signature: /Gerard A. Messina/

REPLY UNDER 37 C.F.R. § 1.116

SIR:

In response to a December 3, 2008 Final Office Action in the above-identified application, please amend, without prejudice, the above-captioned application as follows.

Amendments to the Claims are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.